

Table1. Specifications for Lead foaming and cropping machine

Sl.No	Specification	Specification value	Compliance
1	Flat Pack Press complete	Flat Pack Press complete with 3" stroke and safety approved dual palm switches for lead forming of SMT devices	
2	Die	<p>1. Single stage, two side adjustable die to form and cut flat pack SMD ICs to a surface mount gull wing Reflow configuration.</p> <p>2. Die should include one digital micrometer for stand -off height and Linear Digital scale for body- to- bend, component body and overall cut length adjustments.</p> <p>3. The die mechanism shall be with interchangeable inserts option for various lead thickness as mentioned in SI No. 6</p>	
3	Body to First bend length	Adjustable 0.91mm – 7.25 mm	
4	Foot length	Adjustable to 1.27 mm	
5	Stand -off-height	Adjustable 0.00 – 4.75 mm	
6.1	Fixed with upper and Lower inserts for lead thickness of 0.15mm		
6.2	Interchangeable upper and lower inserts (Spare Accessories)	<p>1. For lead thickness of 0.23mm</p> <p>2. For lead thickness of 0.30mm</p>	
7	Process sequence	Two sides of the component at a time	
8	Working Pressure	80 PSI approx.	
9	Warranty	Minimum Two year	
10	AMC	Non comprehensive AMC for 5 years shall be quoted along with equipment quote. This will also be considered for evaluating L1	
11	Delivery	At IISU	
12	Sample devices for trial operation	Any sample required for trial operation and demonstration shall be vouched by party. IISU will not supply any samples. The dummy components formed using this machine for tool tryout and inspection must be sent to IISU along with the consignment.	
13	Authorized service Centres	Authorized service Centres in India shall be specified along with quote	
14	Installation and Training	Shall be done at IISU	
15	Spares	Essential spares shall be quoted separately	